

Patent claims

1. A building board for use as a ceiling or wall element in house building, characterized by a plurality of OSBs (1, 2, 3; 1a, 2a, 3a; 1b, 2b, 3b) which are disposed side by side and are bonded together in multiple layers.

2. The building board as claimed in claim 1, characterized in that the layers of a plurality of boards (1, 2, 3; 1a, 2a, 3a; 1b, 2b, 3b) are additionally connected to one another by mechanical connecting means.

3. The building board as claimed in claim 2, characterized in that at least one nail plate (7) is disposed between respectively two layers lying one on top of the other.

4. The building board as claimed in claim 1, characterized in that at least one plastics mat (6) is disposed between two layers lying one on top of the other.

5. The building board as claimed in claim 1, characterized in that interspaces (4) are provided between the boards (1, 2, 3; 1a, 2a, 3a; 1b, 2b, 3b) of a layer.

6. The building board as claimed in claim 5, characterized in that the interspaces (4) are filled with an insulating material (5).

7. The building board as claimed in one or more of the above claims, characterized by a length of 2 - 20 m, especially 2 - 10 m or 4 - 6 m.

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8. The building board as claimed in one or more of the above claims, characterized by a thickness of 50 - 90 mm, especially 100 - 400 mm or 100 - 250 mm.

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